

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): A semiconductor power module, comprising:

a lead frame having a first portion at a first level, a second portion connected to  
~~surrounding~~ the first portion at a second level, and a plurality of terminals connected to the  
second portion;

a power circuit mounted on a top surface of the first portion;

a heat sink having an electrically insulating property and thermal conductivity,  
wherein the heat sink directly contacts a second surface opposite the first surface of the first  
portion of the lead frame; and

a sealer having an electrically insulating property and thermal conductivity, wherein  
the sealer ~~that~~ covers the power circuit.

Claim 2 (original): The semiconductor power module of claim 1, wherein the first portion of  
the lead frame is centrally positioned within the lead frame.

Claim 3 (original): The semiconductor power module of claim 1, wherein the power circuit  
includes a power semiconductor element.

Claim 4 (original): The semiconductor power module of claim 1, wherein the first surface of  
the first portion is a top surface and wherein the second surface of the first portion is a bottom  
surface.

Claim 5 (original): The semiconductor power module of claim 1, further comprising a  
control circuit that drives the power circuit.

Claim 6 (original): The semiconductor power module of claim 1, further comprising a heat  
detection circuit that detects the heat produced by the power circuit.

Claim 7 (cancelled).

Claim 8 (previously presented): The semiconductor power module of claim 1, wherein the heat sink is adhered to at least one of the lead frame and the sealer with an adhesive.

Claim 9 (original): The semiconductor power module of claim 8, wherein the adhesive contains a filler that includes at least one compound selected from the group consisting of  $\text{Al}_2\text{O}_3$ , AlN and BeO.

Claim 10 (previously presented): The semiconductor power module of claim 1, wherein the heat sink and the sealer each have grooves or rings and wherein the heat sink and the sealer are connected to each other by means of the grooves or the rings.

Claim 11 (previously presented): The semiconductor power module of claim 1, wherein the heat sink is sheet-shaped and comprises at least one compound selected from the group consisting of  $\text{Al}_2\text{O}_3$ , AlN and BeO.

Claims 12-18 (cancelled):

**Amendments to the Drawings:**

The attached sheet of drawings includes new Figs. 4 and 5. In Fig. 4, the previously omitted heat sink adhered to at least one of the lead frame and the sealer with an adhesive has been added. In Fig. 5, the previously omitted heat sink and sealer connected to each other by means of grooves or rings has been added. Support for the requested changes may be found throughout the specification, drawings, and claims as originally filed. No new matter has been added.

Attachment: Replacement Sheet